

Title (en)  
ELECTROPLATING DEVICE AND METHOD

Title (de)  
VORRICHTUNG UND VERFAHREN ZUR GALVANISCHEN BESCHICHTUNG

Title (fr)  
PROCÉDÉ ET DISPOSITIF DE REVÊTEMENT GALVANIQUE

Publication  
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Application  
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Abstract (en)  
[origin: WO2007118810A2] The invention relates to a device for electroplating at least one electrically conductive substrate or a structured or electrically conductive surface covering the whole area of a non-conductive substrate. Said device comprises at least one bath, an anode and a cathode. The bath contains an electrolyte solution, which comprises at least one metal salt and from which metal ions are deposited on electrically conductive surfaces of the substrate to form a metal layer, as the cathode is brought into contact with the surface of the substrate to be coated and said substrate is conveyed through the bath. The cathode comprises at least two discs (2, 4, 10) that are rotatably mounted on a respective shaft (1, 5, 14), said discs (2, 4, 10) intermeshing. The invention also relates to a method for electroplating at least one substrate, said method being carried out in a device according to the invention. The invention further relates to the use of said device for electroplating electrically conductive structures situated on an electrically non-conductive support.

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